CLAIM AMENDMENTS

Claims 1-3 (canceled)

Claim 4 (currently amended): A light source ~~as claimed in Claim 1, wherein~~ comprising:

a planar substrate having an upper surface and a lower surface, a portion of the upper surface defining a recess having a side wall tapering outwards towards the upper surface, the substrate ~~defines~~ defining first and second vias extending between the upper and lower surfaces,

a light emitting diode mounted in the recess of the substrate adjacent the side walls,

a first electrically-conductive interconnect extending between the upper and lower surfaces, the first interconnect having a terminal on the upper surface coupled to the light emitting diode and an exposed pad on the lower surface for coupling to external circuitry,

a second electrically-conductive interconnect extending between the upper and lower surfaces, the second interconnect having a terminal on the upper surface coupled to the light emitting diode and a conductive pad on the lower surface for coupling to external circuitry, a portion of each of the first and second interconnects extending through the first and second vias respectively, and

a transparent encapsulated material bonded to the first surface of the substrate to encapsulate the light emitting diode, the material being molded to form an ellipsoidal dome over the light emitting diode.

Claim 5 (canceled).

Claim 6 (currently amended): A light source ~~as claimed in Claim 1 wherein~~ comprising:

a planar substrate having an upper surface and a lower surface, a portion of the upper surface defining a recess having a side wall tapering outwards towards the upper surface,

a light emitting diode mounted in the recess of the substrate adjacent the side walls,

a first electrically-conductive interconnect extending between the upper and lower surfaces, the first interconnect having a terminal on the upper surface coupled to the light emitting diode and an exposed pad on the lower surface for coupling to external circuitry,

a second electrically-conductive interconnect extending between the upper and lower surfaces, the second interconnect having a terminal on the upper surface coupled to the light emitting diode and a conductive pad on the lower surface for coupling to external circuitry, and

a transparent encapsulated material bonded to the first surface of the substrate to encapsulate the light emitting diode, the material being molded to form an ellipsoidal dome over the light emitting diode, the ellipsoidal dome ~~formed by the transparent encapsulant material has~~ having a major axis equal to the length of the planar substrate and a minor axis equal to the width of the substrate.